

## WE CLAIM

1. A method of manufacturing an ink jet printhead, the method comprising the steps of:

- 5        depositing a layer of etch stop material on a front side of a wafer substrate;  
      etching the wafer substrate up to the etch stop material to define a plurality of  
nozzle chambers and so that portions of the etch stop layer define roof walls for respective  
nozzle chambers; and  
      etching each said portion to form at least one ink ejection port in each said portion.

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2. A method as claimed in claim 1, which includes the step of fabricating, with  
integrated circuit fabrication techniques, drive circuitry on a back side of the wafer  
substrate.

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3. A method as claimed in claim 2, which includes the step of fabricating, with  
integrated circuit fabrication techniques, a plurality of actuators so that an actuator is  
electrically connected to the drive circuitry and is operatively positioned with respect to  
each nozzle chamber.

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4. An ink jet printhead chip that is manufactured in accordance with an integrated  
circuit fabrication technique, the printhead chip comprising  
a wafer substrate that defines a plurality of nozzle chambers as a result of an etching  
process;

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an etch stop layer positioned on a front side of the wafer substrate so that portions of  
the etch stop layer define a roof wall for each nozzle chamber, each said portion defining at  
least one ink ejection port, also a result of an etching process carried out on each portion;  
and

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a plurality of actuators arranged on a back side of the wafer substrate, each actuator  
being operatively positioned relative to each respective nozzle chamber to eject ink from  
the nozzle chambers.

5. An ink jet printhead chip as claimed in claim 4, which defines a micro electro-  
mechanical system.

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